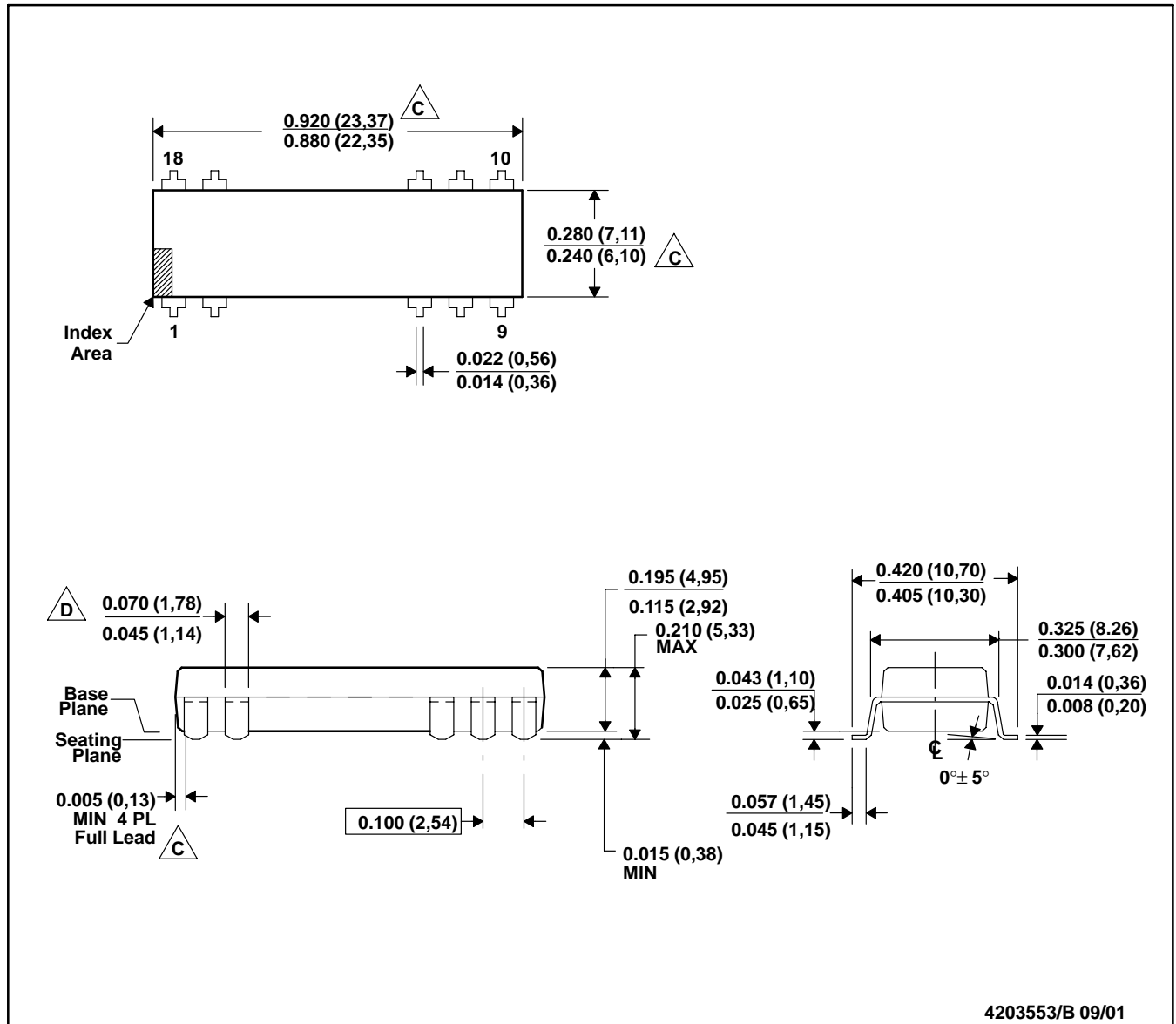


## DVS (R-PDSO-G10/18)

## PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 (0,25).
  - Maximum dimension does not include dambar protrusions. Dambar protrusions shall not exceed 0.010 (0,25)
  - Distance between leads including dambar protrusions to be 0.005 (0,13) minimum.
  - A visual index feature must be located within the cross-hatched area.
  - For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.

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